



**P-Ch 200V Fast Switching MOSFETs**

**Description**

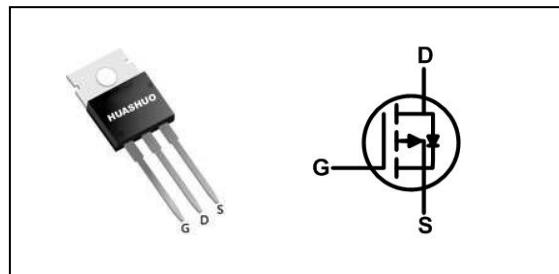
The HSP25P20 uses advanced trench MOSFET technology to provide excellent  $R_{DS(ON)}$  and gate charge for use in a wide variety of other applications.

The HSP25P20 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**Product Summary**

$V_{DS}$	-200	V
$R_{DS(ON),typ}$	300	$m\Omega$
$I_D$	-25	A

**TO220 Pin Configuration**



**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-200	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_c=25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-25	A
$I_D@T_c=100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-15	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-53	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	120	mJ
$I_{AS}$	Avalanche Current	22	A
$P_D@T_c=25^\circ C$	Total Power Dissipation <sup>4</sup>	100	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	1.25	°C/W



**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-200	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_D=-6\text{A}$	---	300	350	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=-250\mu\text{A}$	-2.0	-2.8	-4.0	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-160\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$ , $I_D=-6\text{A}$	---	23	---	S
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-100\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_D=-6\text{A}$	---	56	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	11	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	8.5	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-100\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_G=6\Omega$ , $I_D=-6\text{A}$	---	33	---	ns
$T_r$	Rise Time		---	19	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	149	---	
$T_f$	Fall Time		---	50	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-75\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	3600	---	pF
$C_{\text{oss}}$	Output Capacitance		---	455	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	186	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-25	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.3	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=-75\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $L=0.5\text{mH}$ , $I_{\text{AS}}=-22\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



## P-Ch 200V Fast Switching MOSFETs

### Typical Characteristics

Figure 1. Output Characteristics

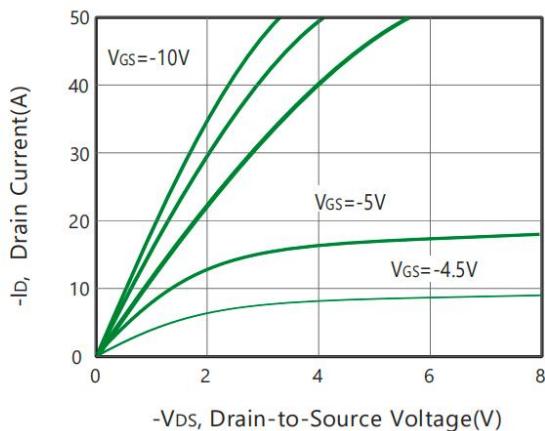


Figure 3. On-Resistance vs.  
Gate-Source Voltage

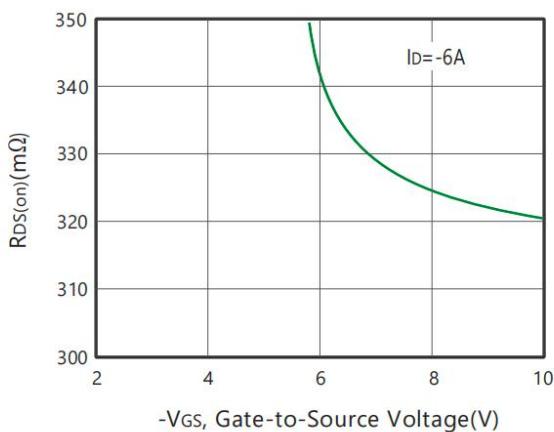


Figure 5. Gate Threshold Variation  
with Temperature

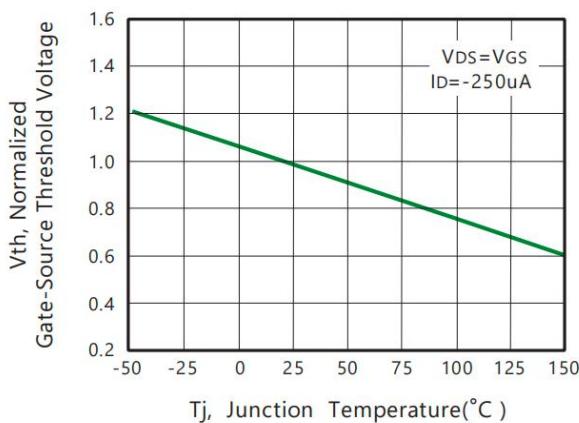


Figure 2. Body Diode Forward Voltage  
Variation with Source Current

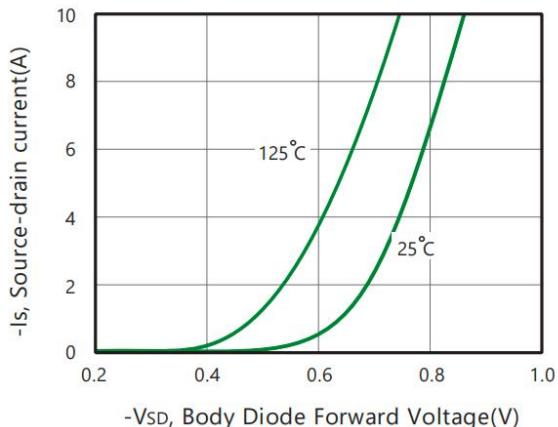


Figure 4. On-Resistance Variation with  
Drain Current and Temperature

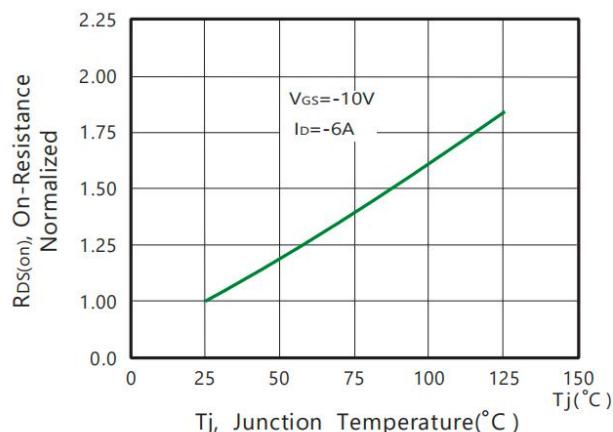


Figure 6. Gate Charge

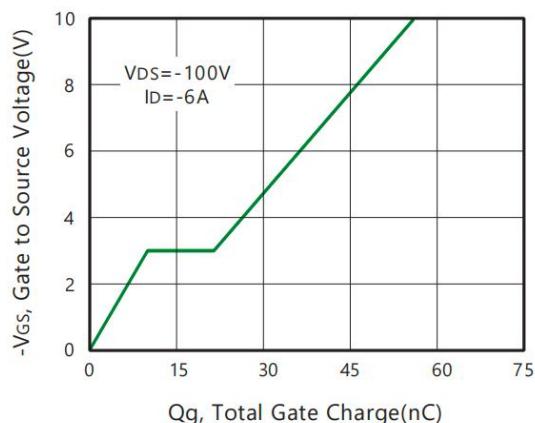




Figure 7. Capacitance

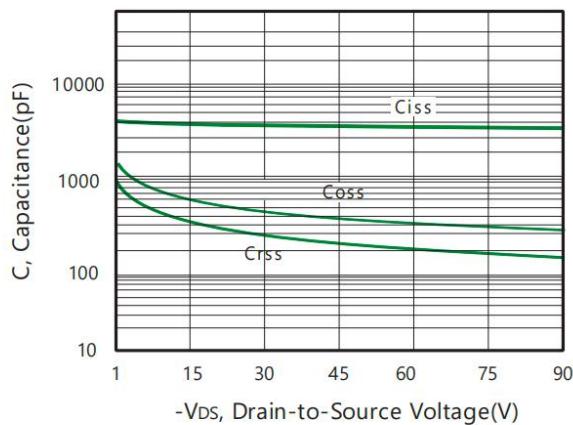


Figure 8. Maximum Safe Operating Area

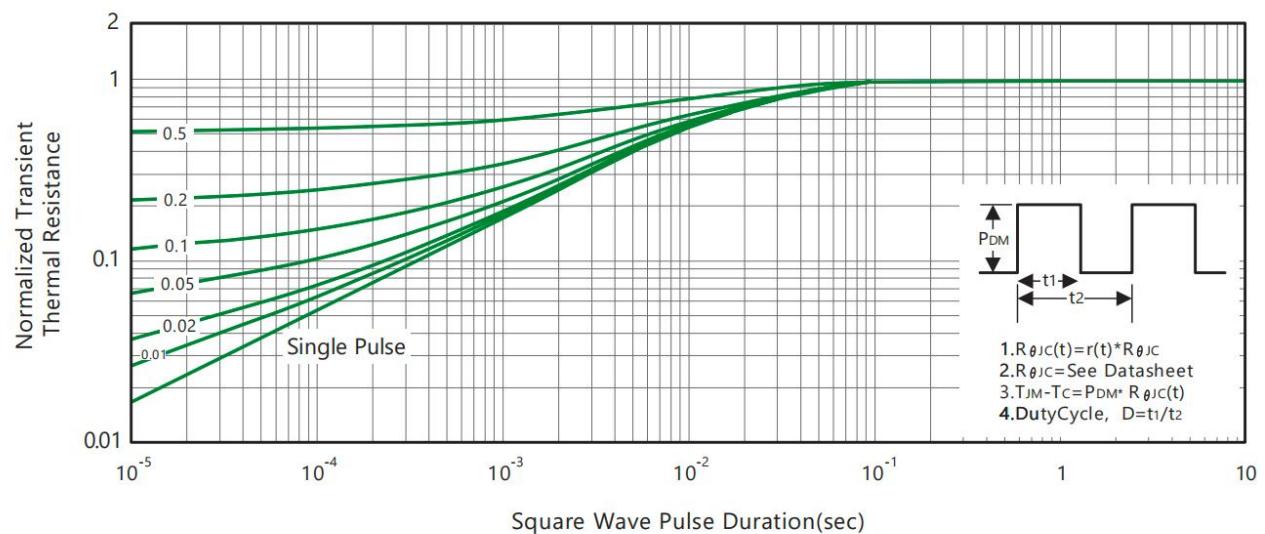
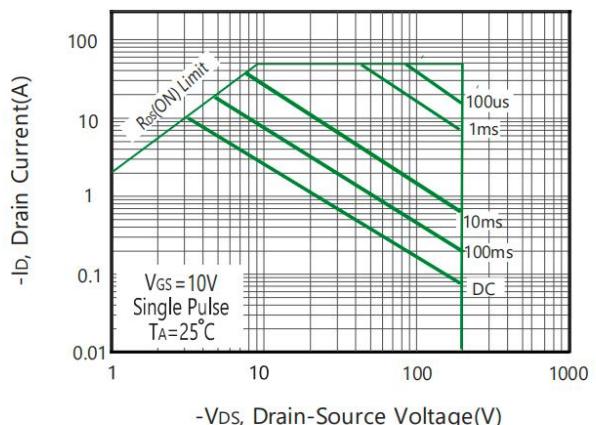
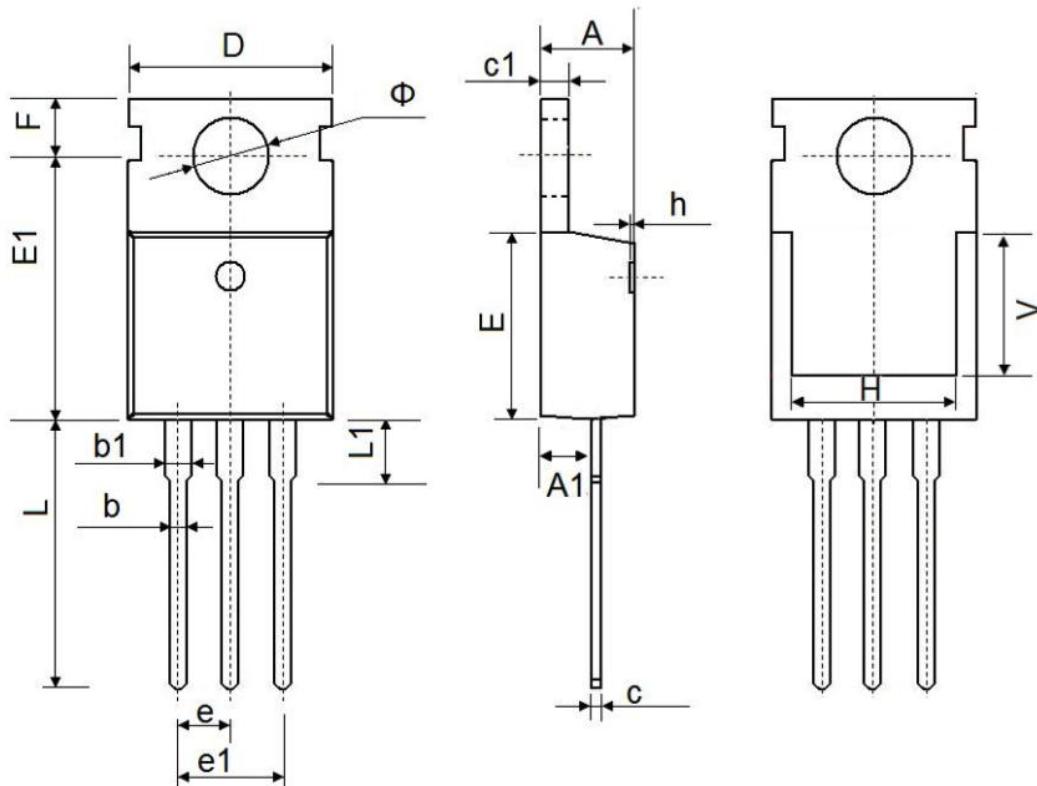


Figure 9. Normalized Thermal Transient Impedance Curve



## TO-220 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max
A	4.300	4.700	0.169	0.185
A1	2.200	2.600	0.087	0.102
b	0.700	0.950	0.028	0.037
b1	1.170	1.410	0.046	0.056
c	0.450	0.650	0.018	0.026
c1	1.200	1.400	0.047	0.055
D	9.600	10.400	0.378	0.409
E	8.8500	9.750	0.348	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.750	14.300	0.502	0.563
L1	2.850	3.950	0.112	0.156
V	7.500 REF.		0.295 REF.	
Φ	3.400	4.000	0.134	0.157